




PCN Number:	20230530001.1		PCN Date:	May 30, 2023					
Title:	Qualification of LFAB as an additional Wafer Fab site option for select devices								
Customer Contact:	PCN Manager		Dept:	Quality Services					
Proposed 1st Ship Date:	Aug 30, 2023		Sample Requests accepted until:	Jun 30, 2023*					
*Sample requests received after June 30, 2023 will not be supported.									
Change Type:									
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design	<input type="checkbox"/>	Wafer Bump Material				
<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Data Sheet	<input type="checkbox"/>	Wafer Bump Process				
<input type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change	<input checked="" type="checkbox"/>	Wafer Fab Site				
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Wafer Fab Material				
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process	<input type="checkbox"/>	Wafer Fab Process				
PCN Details									
Description of Change:									
Texas Instruments is pleased to announce the addition of LFAB as an additional Wafer Fab site option for the products listed in the "Product Affected" section of this document.									
Current Fab Site			Additional Fab Site						
Current Fab Site	Process	Wafer Diameter	New Fab Site	Process	Wafer Diameter				
TSMC-F14	F021	300mm	LFAB	F65	300mm				
DMOS6	F65	300mm							
Qual details are provided in the Qual Data Section.									
Reason for Change:									
Continuity of supply									
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):									
None									
Changes to product identification resulting from this PCN:									
Current Fab Site Information:									
Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City						
DMOS6	DM6	USA	Dallas						
TSMC-F14	T14	TWN	Tainan City						
Additional Fab Site Information:									
New Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City						
LFAB	LHI	USA	Lehi						
Sample product shipping label (not actual product label)									
<div style="display: flex; justify-content: space-between; align-items: flex-start;"> <div style="width: 30%;">  <p>TEXAS INSTRUMENTS</p> <p>MADE IN: Malaysia 2DC: 20:</p> <table border="1" style="font-size: small;"> <tr> <td>MSL 2 / 260C / 1 YEAR</td> <td>SEAL DT</td> </tr> <tr> <td>MSL 1 / 235C / UNLIM</td> <td>03/29/04</td> </tr> </table> <p>OPT: ITEM: 39</p> <p>LBL: 5A (L)T0:1750</p> </div> <div style="width: 15%; text-align: center;">  </div> <div style="width: 15%; text-align: center;">  </div> <div style="width: 40%;"> <p>(1P) SN74LS07NSR</p> <p>(Q) 2000 (D) 0336</p> <p>(31T) LOT: 3959047MLA</p> <p>(4W) TKY (1T) 7523483SI2</p> <p>(P)</p> <p>(2P) REV: (V) 0033317</p> <p>(20L) CSO: SHE (21L) CCO: USA</p> <p>(22L) ASO: MLA (23L) ACO: MYS</p> </div> </div>						MSL 2 / 260C / 1 YEAR	SEAL DT	MSL 1 / 235C / UNLIM	03/29/04
MSL 2 / 260C / 1 YEAR	SEAL DT								
MSL 1 / 235C / UNLIM	03/29/04								

Product Affected:

CC2640R2FRGZR	CC2640R2FRHBT	CC2640R2LRGZR	FRE014RHBR
CC2640R2FRGZT	CC2640R2FRSMR	CC2640R2LRHBR	
CC2640R2FRHBR	CC2640R2FRSMT	FRE014RGZR	

Qualification Report
Approve Date 22-May-2023

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: CC2640R2FRGZR	Qual Device: CC2640R2FRSMR	QBS Reference: CC2640R2Fx	QBS Reference: CC2642R1FRGZR	QBS Reference: TMS320F28379SPTPO
HAST	A2	Biased HAST	110C/85%RH	264 Hours	-	-	3/231/0	2/154/0	-
UHAST	A3	Autoclave	121C/15psig	96 Hours	-	-	3/231/0	-	-
UHAST	A3	Unbiased HAST	110C/85%RH	264 Hours	-	-	-	2/154/0	-
TC	A4	Temperature Cycle	-55C/125C	700 Cycles	-	1/77/0	3/231/0	-	-
TC	A4	Temperature Cycle	-55C/125C	1000 Cycles	-	-	-	2/154/0	-
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	-	3/215/0	-	-
HTSL	A6	High Temperature Storage Life	150C	500 Hours	-	-	-	2/90/0	-
HTOL	B1	Life Test*	125C	1000 Hours	-	-	3/231/0	-	3/231/0
HTOL	B1	Life Test*	125C	500 Hours	-	-	-	2/154/0	-
EDR	B3	NVM Data Retention*	150C	1000 Hours	-	-	-	-	3/231/0
EDR	B3	NVM Data Retention*	150C	500 Hours	-	-	-	2/78/0	-

Type	#	Test Name	Condition	Duration	Qual Device: CC2640R2FRGZR	Qual Device: CC2640R2FRSMR	QBS Reference: CC2640R2Fx	QBS Reference: CC2642R1FRGZR	QBS Reference: TMS320F28379SPTPO
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	-	-	-	3/2400/0
ESD	E2	ESD CDM	-	500 Volts	1/3/0	1/3/0	1/3/0	-	-
ESD	E2	ESD HBM	-	2000 Volts	1/3/0	-	1/3/0	-	-
LU	E4	Latch-Up	Per JESD78	-	1/3/0	-	1/3/0	-	-

- QBS: Qual By Similarity
- Qual Device CC2640R2FRGZR is qualified at MSL3 260C
- Qual Device CC2640R2FRSMR is qualified at MSL3 260C
- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles
- *HTOL/Life Test and EDR/NVM Data Retention units were W/E precycled prior to these stress tests

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

For questions regarding this notice, e-mails can be sent to the contact shown below or your local Field Sales Representative.

Location	E-Mail
WW Change Management Team	PCN_ww_admin_team@list.ti.com

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